

TFN847

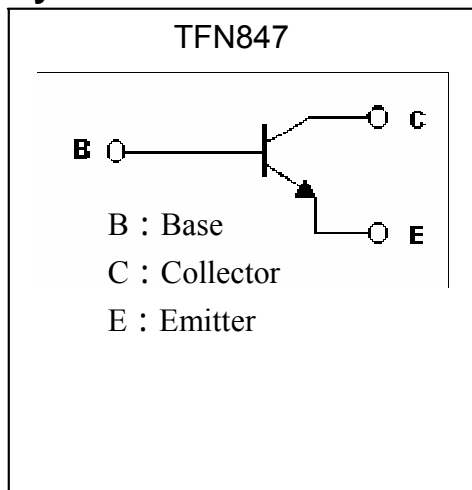
Description

- The TFN847 is designed for general purpose switching and amplification applications.
- Complementary to TFN857.
- Pb-free package

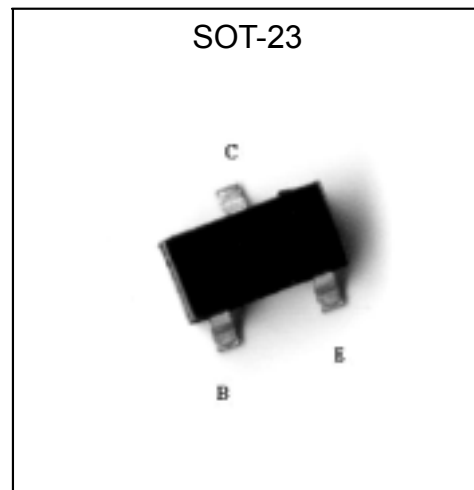
Features

- Low current, $I_{C(max)}=100mA$
- Low voltage, $BV_{CEO}= 45V$.

Symbol



Outline



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	50	V
Collector-Emitter Voltage	V_{CEO}	45	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current (DC)	I_C	100	mA
Collector Current (Pulse)	I_{CP}	200	mA
Power Dissipation	P_d	225	mW
Junction Temperature	T_j	150	°C
Storage Temperature	T_{stg}	-55~+150	°C

**Characteristics (Ta=25°C)**

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	50	-	-	V	I _C =10μA
BV _{CEO}	45	-	-	V	I _C =1mA
BV _{EBO}	6	-	-	V	I _E =10μA
I _{CB0}	-	-	15	nA	V _{CE} =30V
I _{EBO}	-	-	100	nA	V _{EB} =5V
*V _{CE(sat)} 1	-	-	250	mV	I _C =10mA, I _B =0.5mA
*V _{CE(sat)} 2	-	-	600	mV	I _C =100mA, I _B =5mA
*V _{BE(sat)} 1	-	700	-	mV	I _C =10mA, I _B =0.5mA
*V _{BE(sat)} 2	-	900	-	mV	I _C =100mA, I _B =5mA
*V _{BE(on)} 1	580	660	700	mV	V _{CE} =5V, I _C =2mA
*V _{BE(on)} 2	-	-	770	mV	V _{CE} =5V, I _C =10mA
*h _{FE}	110	-	800	-	V _{CE} =5V, I _C =2mA
f _T	100	-	-	MHz	V _{CE} =5V, I _E =10mA, f=100MHz
Cob	-	2.5	-	pF	V _{CB} =10V, I _E =0A, f=1MHz

*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

Classification of h_{FE} :

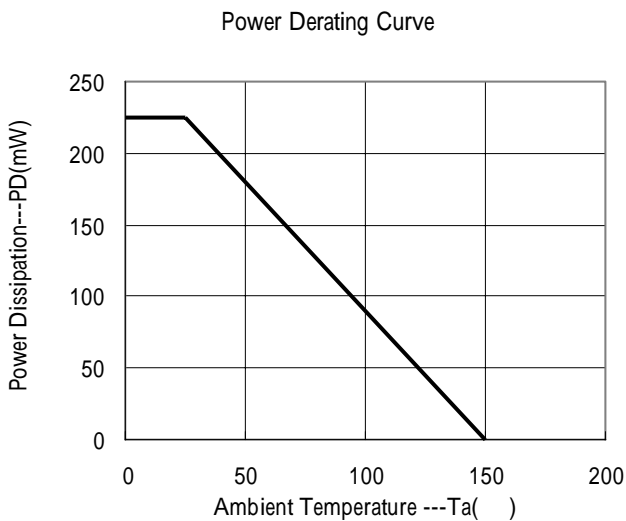
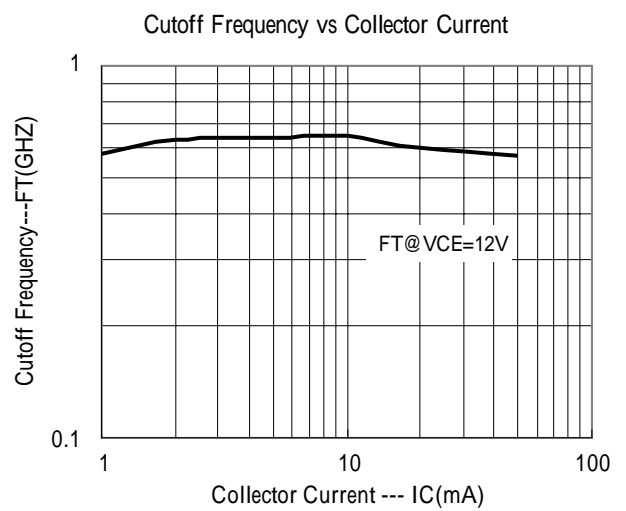
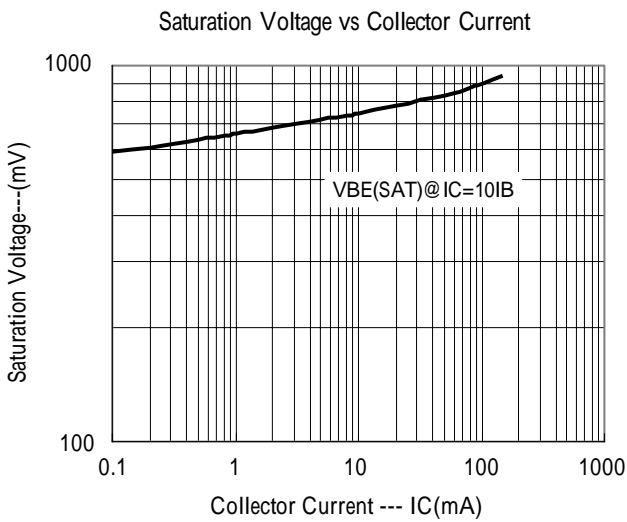
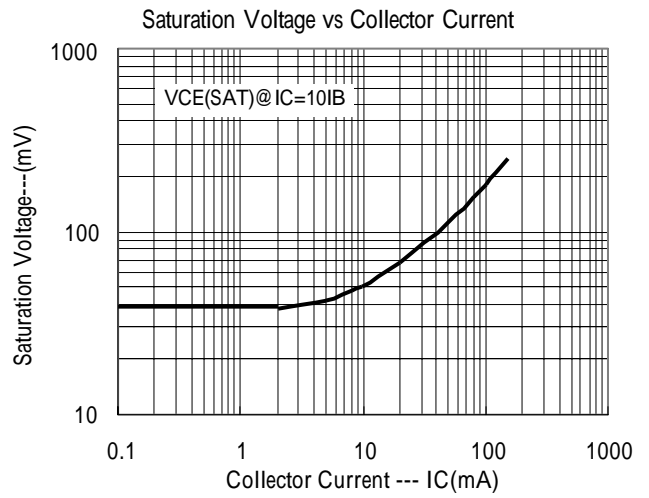
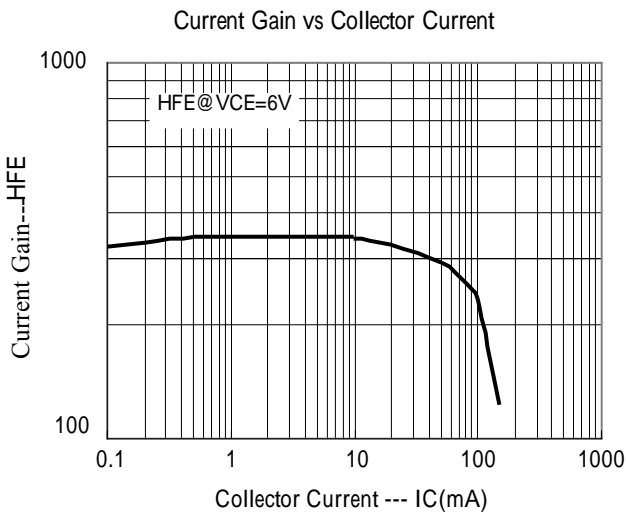
Rank	A	B	C
Range	110--220	200--450	420--800

Ordering Information

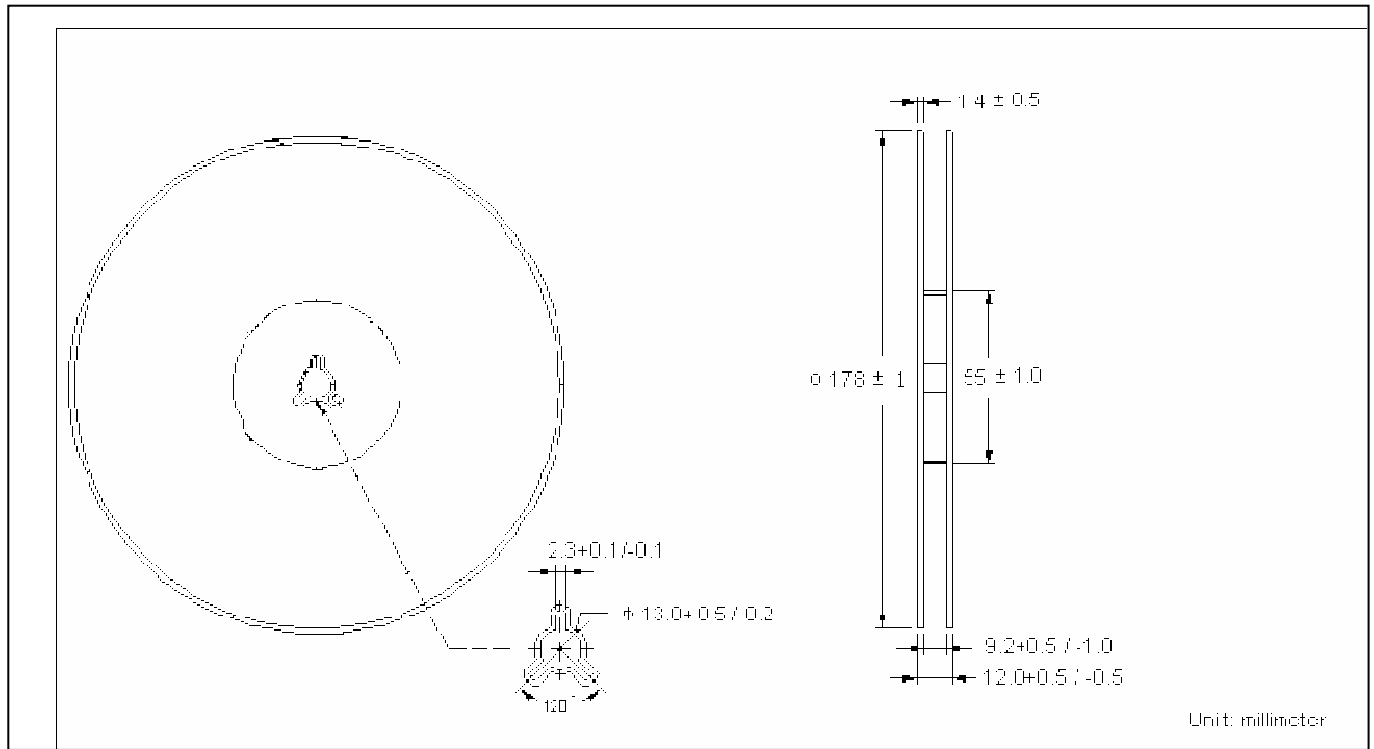
Device	Package	Shipping	Marking
TFN847 A-rank	SOT-23 (Pb-free package)	3000 pcs / Tape & Reel	1E
TFN847 B-rank	SOT-23 (Pb-free package)	3000 pcs / Tape & Reel	1F
TFN847 C-rank	SOT-23 (Pb-free package)	3000 pcs / Tape & Reel	1G



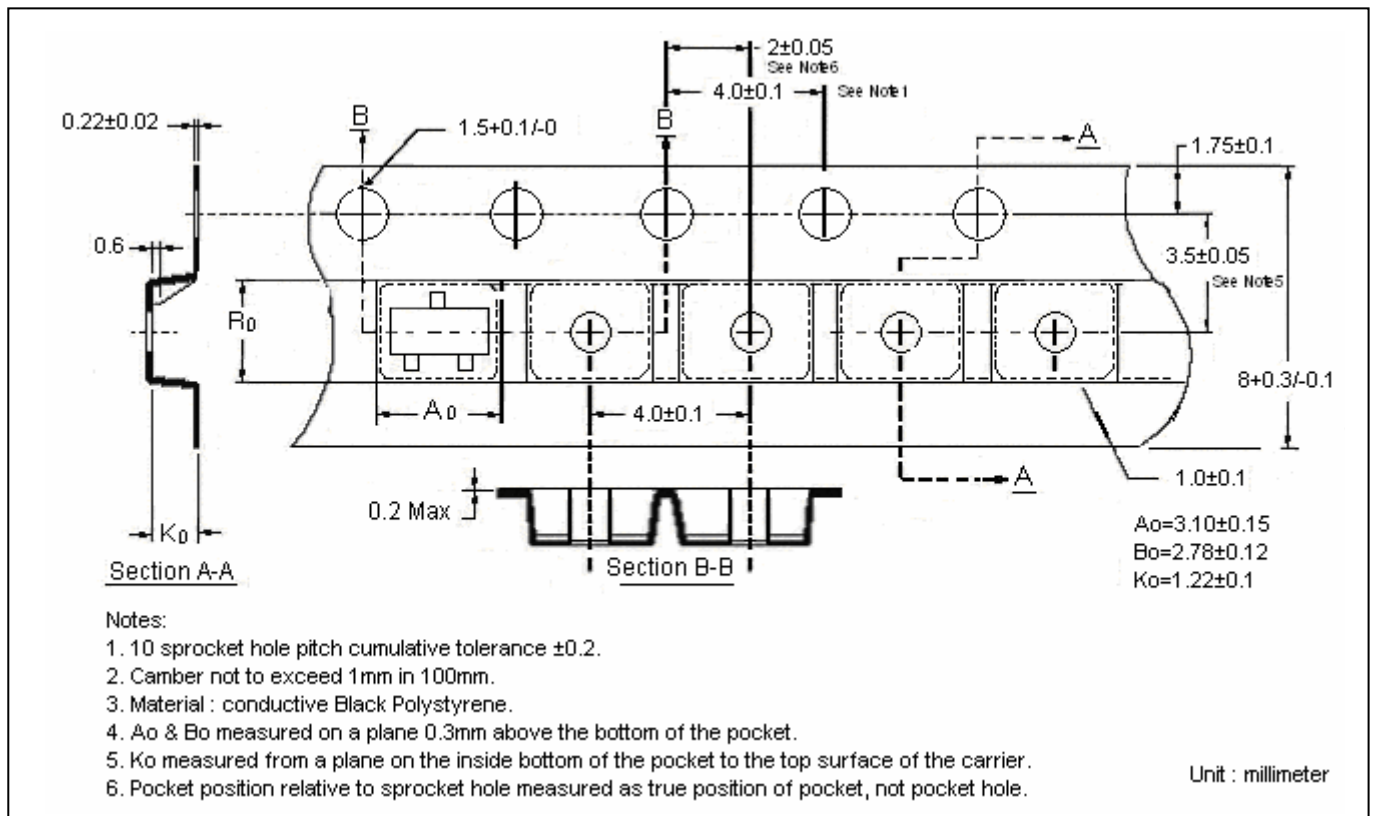
Characteristic Curves



Reel Dimension



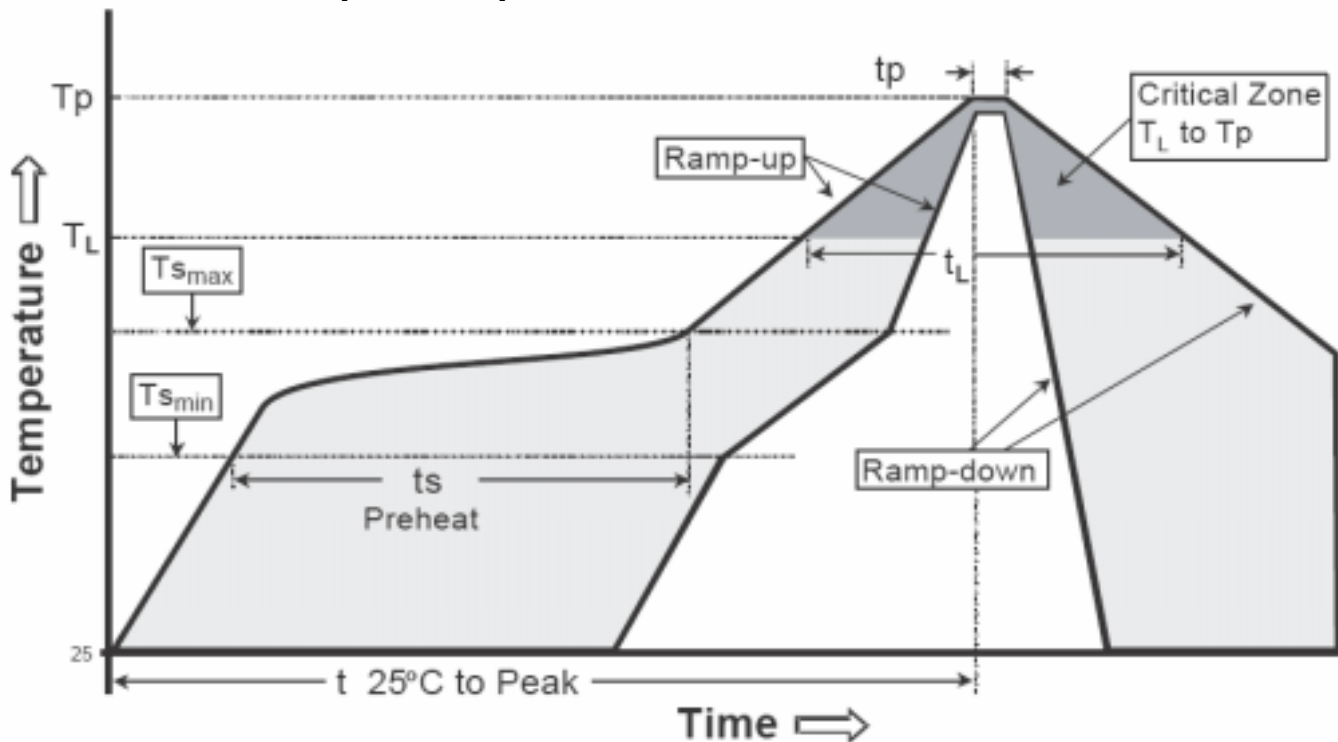
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the packa